

MA2DF62

Silicon Mesa type

For high frequency rectification

■ Features

- Super high speed switching characteristic: $t_{rr} = 15 \text{ ns}$ (typ.)
- Low noise type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	600	V
Non-repetitive peak reverse surge voltage	V_{RSM}	600	V
Forward current (Average) *1	$I_{F(AV)}$	10	A
Non-repetitive peak forward surge current *2	I_{FSM}	40	A
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +150	$^\circ\text{C}$

Note) *1: $T_c = 25^\circ\text{C}$

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Package

- Code
TO-220D-B1
- Pin Name
1: Cathode
2: Anode

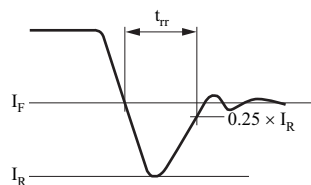
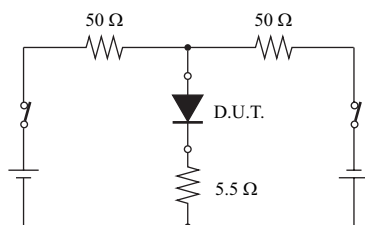
■ Marking Symbol: MA2DF62

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10 \text{ A}$		1.8	2.5	V
Reverse current	I_{RRM}	$V_{RRM} = 600 \text{ V}$			30	μA
Reverse recovery time *	t_{rr}	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}$ $I_{rr} = 0.25 \text{ A}$		15	25	ns
Thermal resistance (j-c)	$R_{th(j-c)}$				3.0	$^\circ\text{C/W}$
Thermal resistance (j-a)	$R_{th(j-a)}$				63	$^\circ\text{C/W}$

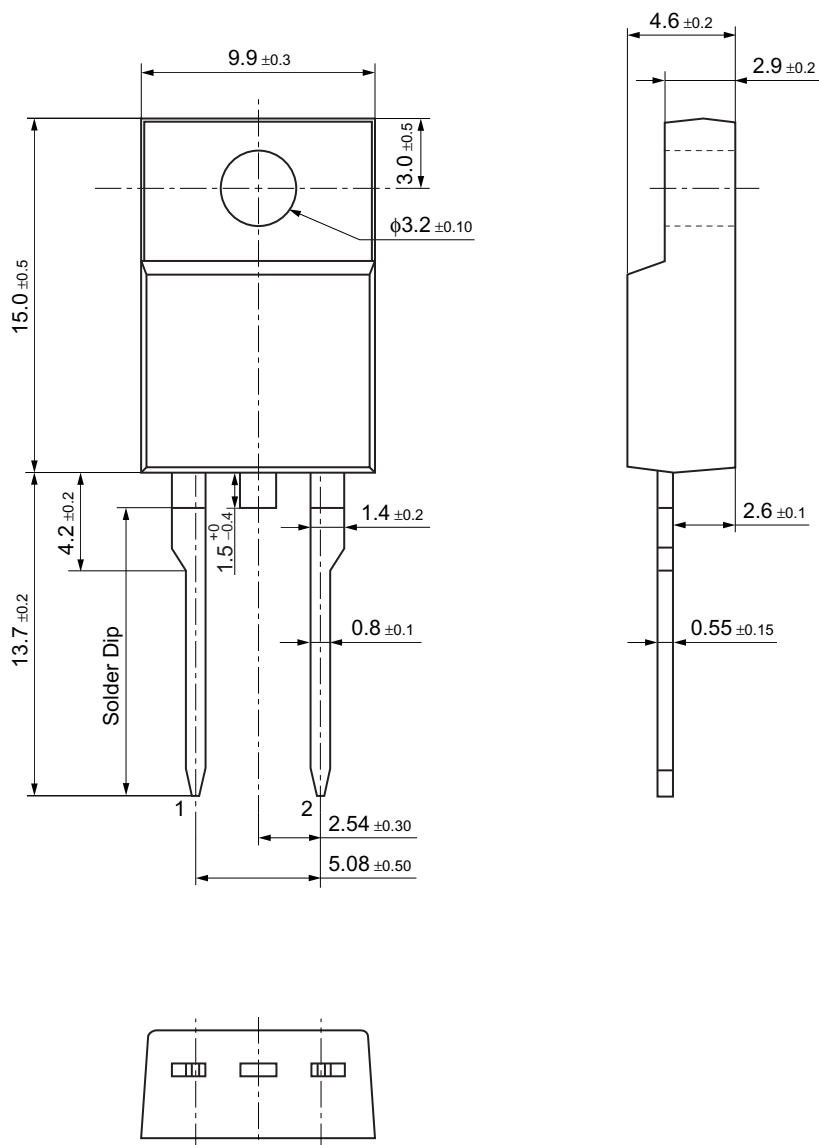
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *: t_{rr} measurement circuit

TO-220D-B1

Unit: mm



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